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lid with adhesive after the CGA integrated circuit package is mounted on the circuit board. The adhesive accommodates any variations in height in the CGA integrated circuit package.

IN THE CLAIMS

Please amend the claims in accordance with the following rewritten claims in clean form. Applicant includes herewith an Attachment for Claim Amendments showing a marked up version of each amended claim.

1. (Amended) A circuit board assembly, comprising:
 - a. a circuit board;
 - b. an integrated circuit package having a substrate with an array of solder columns extending from a bottom surface of the substrate to the circuit board when the integrated circuit package is mounted on the circuit board;
 - c. a lid affixed to the substrate, the lid having a portion that extends beyond an outer periphery of the substrate; and
 - d. at least one support shim disposed between the portion of the lid that extends beyond the outer periphery of the substrate and a portion of the circuit board to which the integrated circuit package is mounted to support the column grid array integrated circuit package against compressive force.

4. (Amended) The apparatus of claim 2 wherein the integrated circuit package is rectangular and the said at least one support shim includes a support shim disposed at each corner of the integrated circuit package.

7. (Amended) The apparatus of claim 6 wherein adhesive is disposed between the top flange of each support shim and the portion of the lid extending beyond the outer periphery of the substrate to affix the support shim to the integrated circuit package and to fill gaps between the top flanges of the support shims and the portion of the lid extending beyond the outer periphery of the substrate.

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8. (Amended) A circuit board assembly, comprising:

- a. a circuit board;
- b. a rectangular column grid array integrated circuit package having a substrate with an array of solder columns extending from a bottom surface;
- c. a lid affixed to the substrate, the lid having a portion that extends beyond an outer periphery of the substrate; and
- d. a support shim disposed at each corner of the column grid array integrated circuit package between the portion of the lid that extends beyond the outer periphery of the substrate and a portion of a circuit board to which the column grid array integrated circuit package is mounted to support the column grid array integrated circuit package against compressive force, each support shim disposed between the lid and the circuit board after the column grid array integrated circuit package has been mounted to the circuit board and secured to at least one of the substrate and lid by adhesive, the adhesive accommodating variations in height in the column grid array integrated circuit package.

13. (Amended) The method of claim 12 and further including the step of affixing the at least one support shim by adhesive to the lid, the adhesive accommodating any variations in height of the integrated circuit package.

14. (Amended) The method of claim 13 wherein the step of affixing the at least one support shim by adhesive to the lid includes filling any gaps between the lid and the at least one support shim with the adhesive.

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15. (Amended) The method of claim 13 wherein the integrated circuit package is rectangular and the step of providing the at least one support shim includes providing at least one support shim at each corner of the integrated circuit package.

16. (Amended) The method of claim 13 wherein the integrated circuit package is rectangular and the step of providing the at least one support shim includes providing at least one support shim at each side of the integrated circuit package.